



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 6344
Yoshio YANASE et al. : Docket No. 2001-0615A
Serial No. 09/856,982 : Group Art Unit 2877
Filed May 30, 2001 : Examiner Sang H. Nguyen

METHOD FOR INSPECTING SEMICONDUCTOR WAFER SURFACE

ADDITIONAL CLAIMS FEE TRANSMITTAL LETTER

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Transmitted herewith is an Amendment in the above-identified application.
Additional fees required as a result of this Amendment are calculated as follows:

	SMALL ENTITY	LARGE ENTITY
Total Claims exceeding 20 (not already paid for): 5 x	(\$ 9 = \$)	or (\$18 = \$90.00)
Indep. Claims exceeding 3 (not already paid for): x	(\$42 = \$)	or (\$84 = \$)
<input type="checkbox"/> Multiple Dep. Claim(s) (if there previously were none): +	(\$140 = \$)	or (\$280 = \$)
Total Additional Fee =	<u>\$</u>	<u>\$90.00</u>

- Small entity status of this application is established by the verified statement under 37 C.F.R. 1.9 and 1.27 which
 is enclosed or
 has been previously submitted.
- A check in the amount of \$90.00 is enclosed.

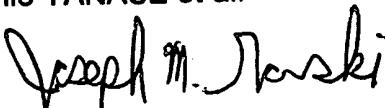
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- Please charge Deposit Account No. 23-0975 the amount of \$ to cover additional fee. The Commissioner is authorized to charge any deficiency associated with this communication or to credit any overpayment to the Deposit Account. The original and two copies of this document are enclosed.

Respectfully submitted,

Yoshio YANASE et al.

By



Joseph M. Gorski
Registration No. 46,500
Attorney for Applicants

JMG/adb
Washington, D.C. 20006-1021
Telephone (202) 721-8200
Facsimile (202) 721-8250
March 13, 2003



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PATENT OFFICE FEE TRANSMITTAL FORM

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Attached hereto is a check in the amount of \$500.00 to cover Patent Office fees relating to filing the following attached papers:

Petition for Extension of Time \$410.00

Additional Claims Fee \$90.00

A duplicate copy of this paper is being submitted for use in the Accounting Division, Office of Finance.

The Commissioner is authorized to charge any deficiency or to credit any overpayment associated with this communication to Deposit Account No. 23-0975, with the EXCEPTION of deficiencies in fees for multiple dependent claims in new applications.

Respectfully submitted,

Yoshio YANASE et al.

By Joseph M. Gorski

Joseph M. Gorski
Registration No. 46,500
Attorney for Applicants

JMG/adb
WENDEROTH, LIND & PONACK, L.L.P.
2033 K St., N.W., Suite 800
Washington, D.C. 20006-1021
Telephone (202) 721-8200
March 13, 2003

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AMENDMENT

Assistant Commissioner for Patents,
Washington, D.C.

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Sir:

Responsive to the Office Action mailed October 15, 2002, the time for responding thereto being extended for two months in accordance with a Petition for Extension submitted herewith, please amend the above-identified application as follows:

IN THE SPECIFICATION AND ABSTRACT:

Please replace the original specification and abstract with the enclosed substitute specification and abstract.

IN THE CLAIMS:

Please cancel claims 1-20.

Kindly add the following new claims 21-45:

21. A method for inspecting a semiconductor wafer surface, comprising:
scanning a semiconductor wafer with a laser beam;